

Fig. 11 a Power dissipation per diode vs. forward current and ambient temperature

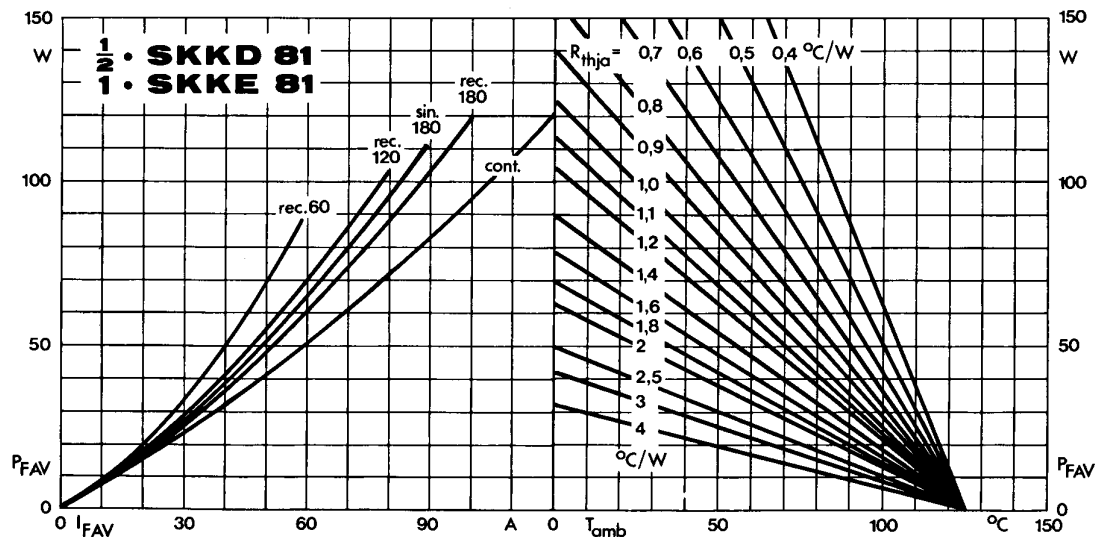


Fig. 11 b Power dissipation per diode vs. forward current and ambient temperature

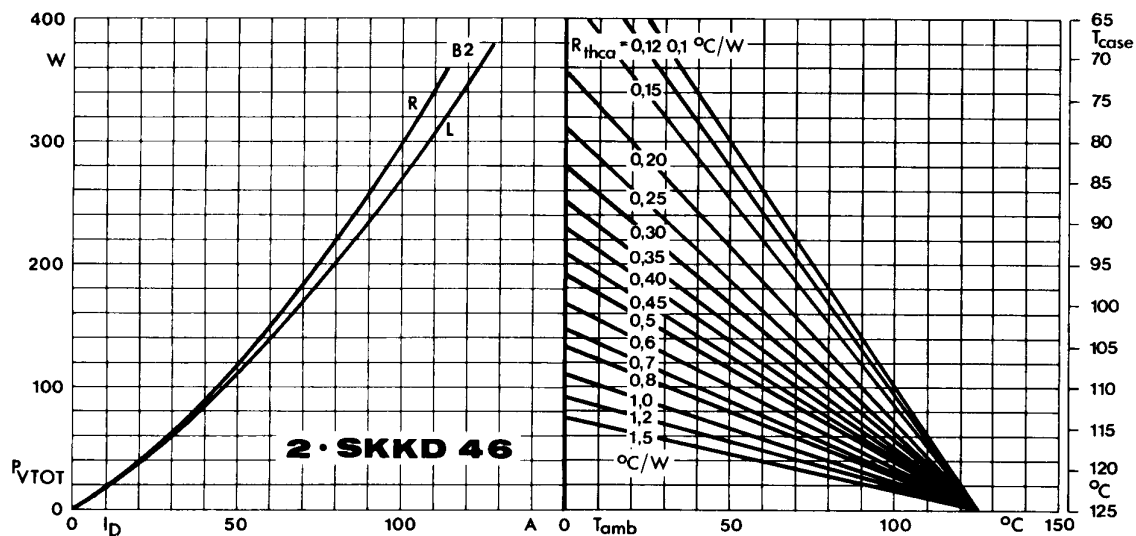


Fig. 12 a Power dissipation of two modules vs. direct current and case temperature

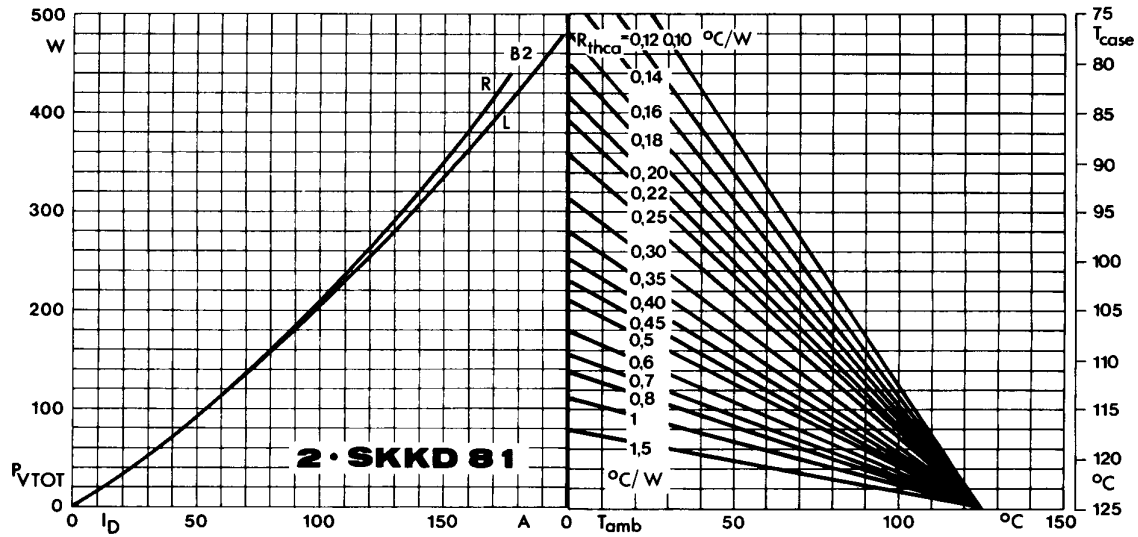


Fig. 12 b Power dissipation of two modules vs. direct current and case temperature

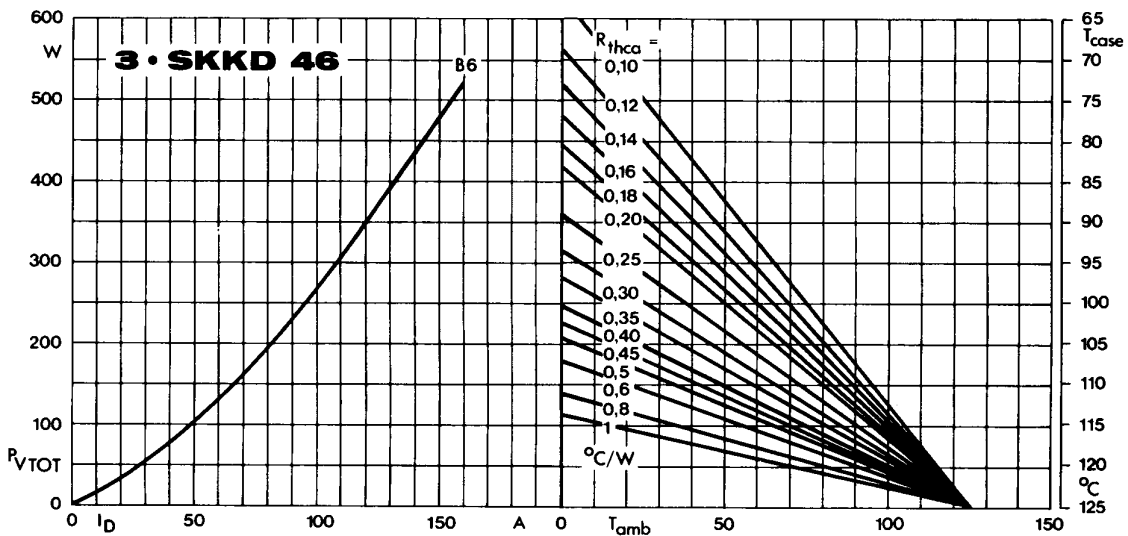


Fig. 13 a Power dissipation of three modules vs. direct current and case temperature

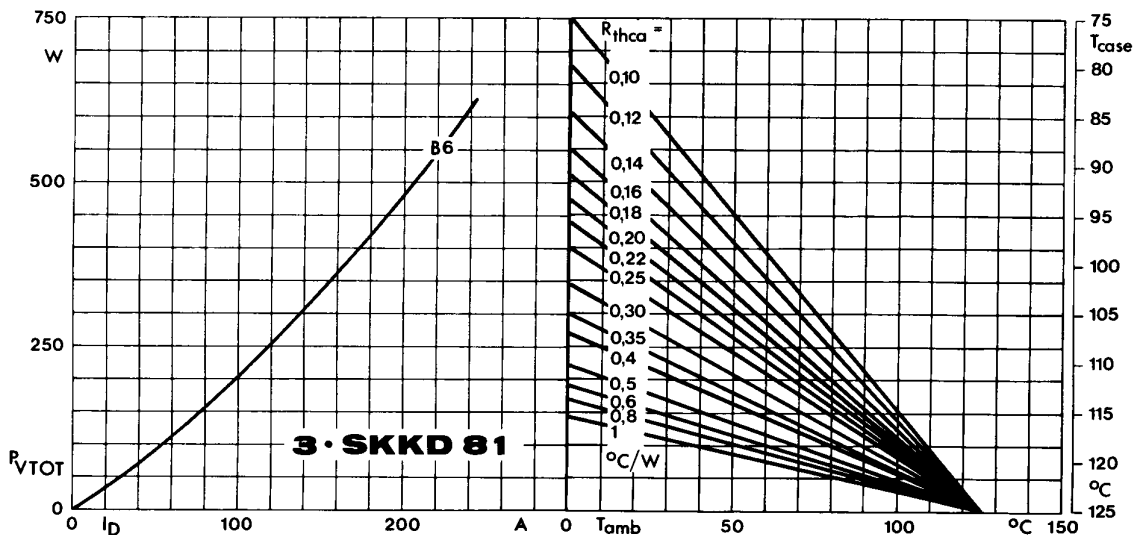


Fig. 13 b Power dissipation of three modules vs. direct current and case temperature

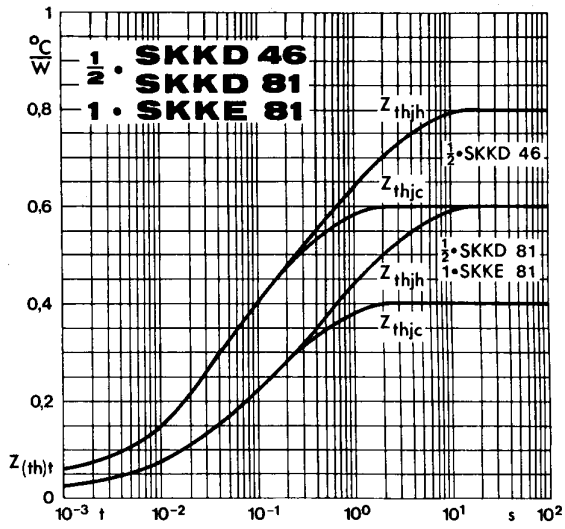


Fig. 14 Transient thermal impedance vs. time

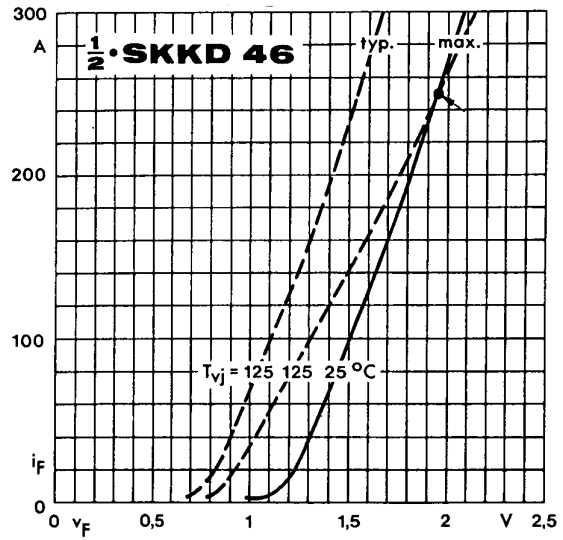


Fig. 15 a Forward characteristics

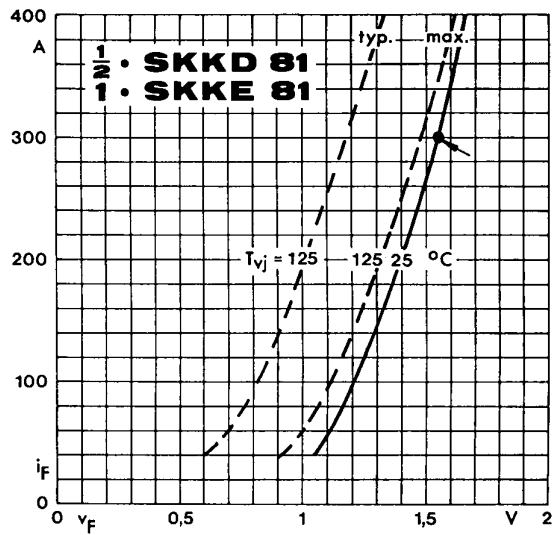


Fig. 15 b Forward characteristics

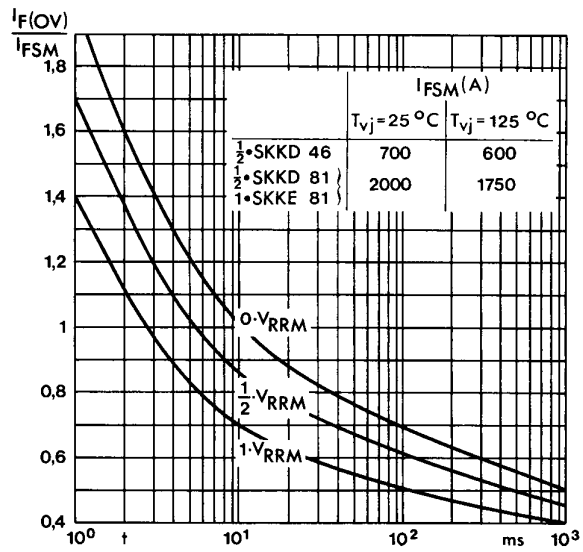


Fig. 16 Surge overload current vs. time

SKKT 19 ... 105

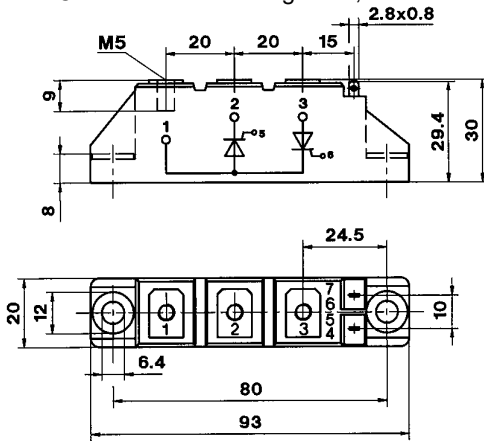
Case A 5

IEC 192-2: A 77 A

JEDEC: TO-240 AA

SEMIPACK® 1

UL recognized, file no. E 63 532



Dimensions in mm

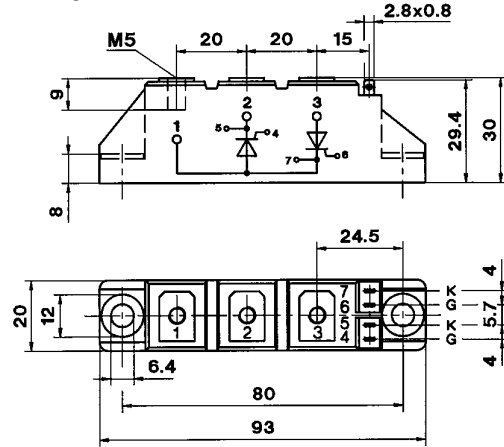
SKKT 20/ ... 106/

Case A 46

IEC 192-2: A 77 A

JEDEC: TO-240 AA

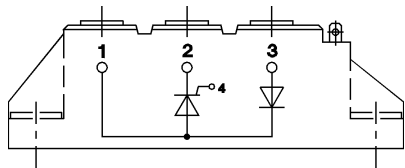
SEMIPACK® 1



Dimensions in mm

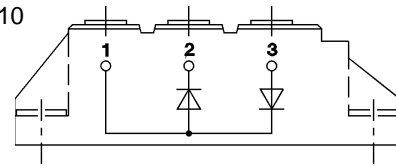
SKKH 26 ... 105

Case A 6



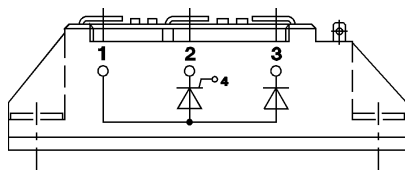
SKKD 26 ... 100

Case A 10



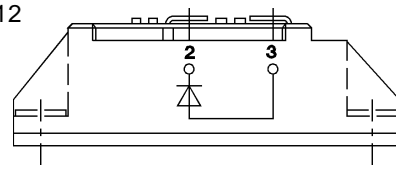
SKNH 56 ... 91

Case A 7



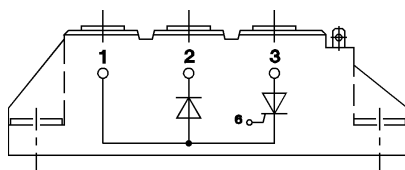
SKKE 81

Case A 12



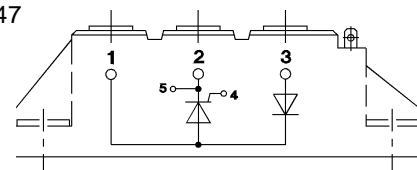
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Case A 9



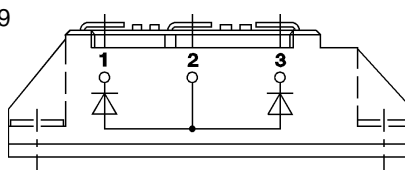
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Case A 47



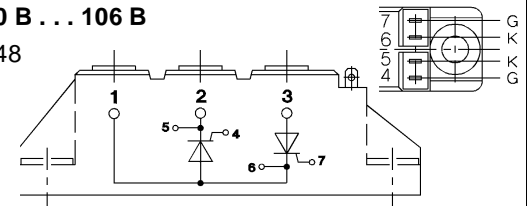
SKND 46 ... 81

Case A 19



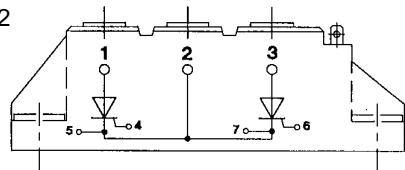
SKKT 20 B ... 106 B

Case A 48



SKMT 92

Case A 72



SKKL 42 ... 106

Case A 59

